

HiPerFRED

 V_{RRM} 1200 V

8 A

40 ns

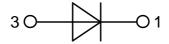
High Performance Fast Recovery Diode Low Loss and Soft Recovery Single Diode

Part number

DSEP8-12A



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-220

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

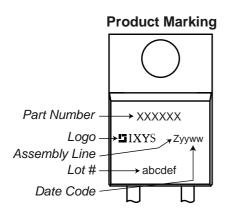
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Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking ve	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			60	μΑ
		V _R = 1200 V	$T_{VJ} = 150$ °C			0.25	mΑ
V _F	forward voltage drop	I _F = 10 A	$T_{VJ} = 25^{\circ}C$			2.94	V
		$I_F = 20 A$				3.57	V
		I _F = 10 A	T _{VJ} = 150°C			1.96	V
		$I_F = 20 A$				2.56	V
I _{FAV}	average forward current	T _C = 135°C	T _{VJ} = 175°C			8	Α
		rectangular d = 0.5					-
V _{F0}	threshold voltage	an advadation and	T _{VJ} = 175°C			1.20	V
\mathbf{r}_{F}	slope resistance	ss calculation only				57	mΩ
R _{thJC}	thermal resistance junction to case	9				2.5	K/W
R _{thCH}	thermal resistance case to heatsin	ık			0.50		K/W
P _{tot}	total power dissipation		$T_C = 25^{\circ}C$			60	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			40	Α
C _J	junction capacitance	$V_R = 600 \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		3		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 ^{\circ}\text{C}$		4		Α
		$I_F = 10 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 100 ^{\circ}\text{C}$		8		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 10 \text{ A; } V_R = 600 \text{ V} \\ -di_F /dt = 200 \text{ A/} \mu \text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}\text{C}$		40		ns
	,	1	$T_{VJ} = 100^{\circ}C$		115		ns



Package	Package TO-220			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal			35	Α	
T _{VJ}	virtual junction temperature		-55		175	°C	
T _{op}	operation temperature		-55		150	°C	
T _{stg}	storage temperature		-55		150	°C	
Weight				2		g	
M _D	mounting torque		0.4	,	0.6	Nm	
F _c	mounting force with clip		20	1	60	N	

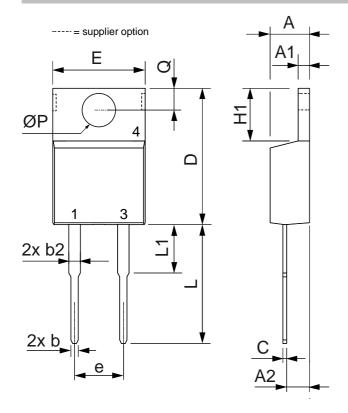


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP8-12A	DSEP8-12A	Tube	50	475912

Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 175 ^{\circ}\text{C}$
$I \rightarrow V_0$)— <u>R</u> o	Fast Diode		
V _{0 max}	threshold voltage	1.2		V
R_{0max}	slope resistance *	54		$m\Omega$



Outlines TO-220



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
Α	4.32	4.82	0.170	0.190
A1	1.14	1.39	0.045	0.055
A2	2.29	2.79	0.090	0.110
b	0.64	1.01	0.025	0.040
b2	1.15	1.65	0.045	0.065
С	0.35	0.56	0.014	0.022
D	14.73	16.00	0.580	0.630
E	9.91	10.66	0.390	0.420
е	5.08	BSC	0.200	BSC
H1	5.85	6.85	0.230	0.270
L	12.70	13.97	0.500	0.550
L1	2.79	5.84	0.110	0.230
ØP	3.54	4.08	0.139	0.161
Q	2.54	3.18	0.100	0.125





Fast Diode

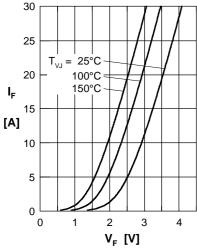


Fig. 1 Forward current I_F versus V_F

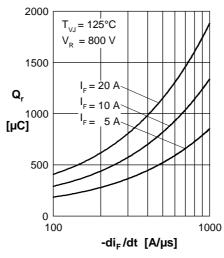


Fig. 2 Typ. reverse recov. charge Q_r versus -di_F/dt

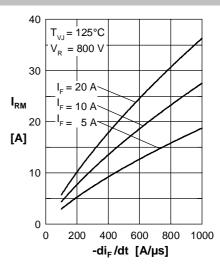


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

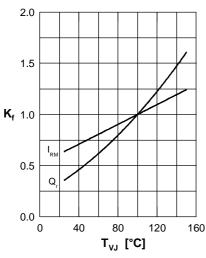


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}

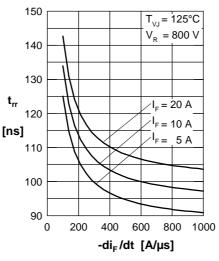


Fig. 5 Typ. recovery time t_{rr} versus $-di_{F}/dt$

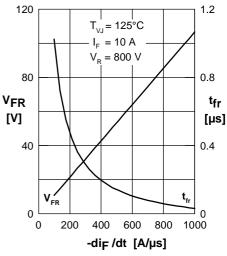


Fig. 6 Typ. peak forward voltage $V_{\rm FR}$ and $t_{\rm fr}$ versus $di_{\rm F}/dt$

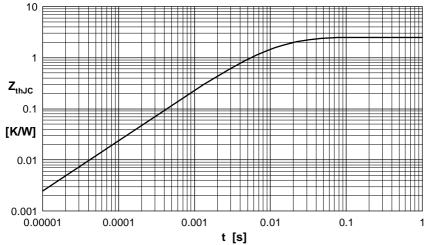


Fig. 7 Transient thermal impedance junction to case

Constants for \mathbf{Z}_{thJC} calculation:

i	R _{thi} (K/W)	t _i (s)
1	0.0200	0.0002
2	0.3000	0.0040
3	0.8000	0.0200
4	1.3800	0.0100